



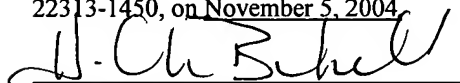
IFW

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

*In Re* Application of: )  
Shen, et al ) Group Art Unit: 2811  
Serial No.: 10/668,985 ) Examiner: Vu, Quang D.  
Filed: September 22, 2003 ) Confirmation Number: 1771  
For: Pad Structure of Semiconductor ) TKHR Docket No.: 251310-1090  
Device for Reducing or Inhibiting ) Sundial Ref.: US1260PA  
Wire Bonding Cracks )

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on November 5, 2004.

  
Signature – Hui Chin Barnhill

RESPONSE TO ELECTION OF SPECIES

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

The Office Action mailed October 5, 2004, has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.